

TITLE OF INVENTION: STACKED PACKAGE

ABSTRACT

A stacked package includes a substrate, conductive pillars, a semiconductor element, electronic elements and an encapsulant. An electronic element mounting area and a conductive pillar mounting area are defined on a surface of the substrate, the conductive pillar mounting area is located between the electronic element mounting area and one of edges of the surface. The conductive pillars are mounted only on the conductive pillar mounting area and electrically connected to the substrate and the semiconductor element, thus the electronic elements can be mounted on the electronic element mounting area where without the conductive pillars to improve electronic performance of the stacked package. The encapsulant is provided between the substrate and the semiconductor element to encapsulate the conductive pillars and the electronic elements and support the semiconductor element.

FIG. 6